Amendments to the Claims:

1-15. (Cancelled)

16. (New) A probe card mountable to a tester for testing a device, wherein the tester includes a test head interphase board, said probe card comprising: a package having solder balls mountable to the test head interphase board, and having electrically conductive material configured to electrically contact bumps on the device.

17. (New) The probe card as recited in claim 16, wherein the probe card does not have any probe pins.

18. (New) The probe card as recited in claim 16, wherein the probe card is configured to make electrical contact with bumps on the device without using probe pins.

19. (New) A method for testing a device under test (DUT), said method comprising: providing a tester which includes a test head interphase board; providing a probe card which includes a package having solder balls mounted to the test head interphase board, and having an electrically conductive surface; providing a device under test (DUT)/load board which is configured to retain a substrate, said tester being connected to a Digital Sampling Oscilloscope (DSO); contacting said electrically conductive surface of said probe card with bumps on the substrate; using said DSO to launch a signal which is received by the substrate, wherein the tester

is configured to obtain a waveform from the DSO and store data in a file, wherein said DSO is configured to receive a reflected signal from the substrate and provide the reflected signal to the tester; and using post processing software to analyze the reflected signal and calculate interconnect impedance versus time data for the DUT.

20. (New) The method as recited in claim 19, further comprising mounting the probe card to a test head inter phase board of the tester.

21. (New) The method as recited in claim 19, further comprising engaging said probe card with the substrate without using any probe pins.